

Absolute Maximum Ratings		T _c = 25 °C, unless otherwise	T _c = 25 °C, unless otherwise specified			
Symbol	Conditions	Values	Units			
V _{DS}		100	V			
ID	T _s = 25 (80) °C	200 (150)	Α			
I _{DM}	1 ms	600	Α			
		± 20	V			
V_{GS} T_{vj} , (T_{stg})		- 40 + 150 (125)	°C			
V_{isol}	AC, 1 min.	2500	V			
Inverse diode						
$I_F = -I_S$		200	Α			
$I_{FM} = -I_{SM}$		600	А			

Power MOSFET Modules

SKM 111AR

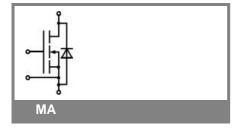
Features

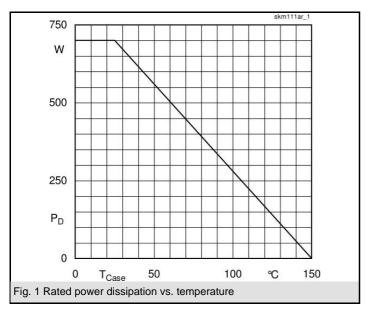
- N Channel, enhancement mode
- Avalanche characteristic
- Short connections and built-in gate resistors to suppress internal oscillations even in critical applications
- Isolated copper baseplate
- All electrical connections on top for easy busbaring
- Large clearances (10 mm) and creepage distances (20 mm)
- UL recognized, file no. E 63 532

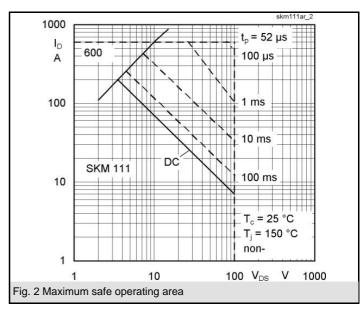
Typical Applications

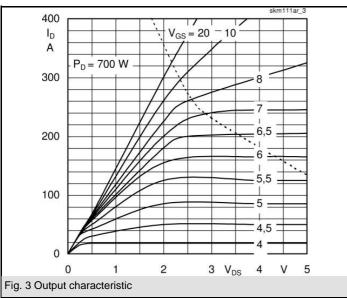
- Switched mode power supplies
- . DC servo and robot drives
- DC choppers
- UPS equipment
- Not suitable for linear amplification

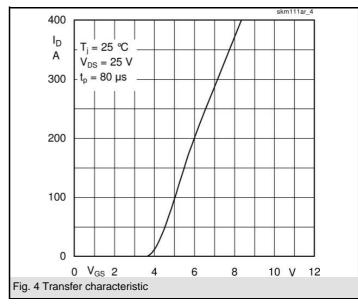
Characteristics		T _c = 25 °C, unless otherwise specified				
Symbol	Conditions	min.	typ.	max.	Units	
V _{(BR)DSS}	V _{GS} = 0 V, I _D = 0,25 mA	100			V	
V _{GS(th)}	$V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$	2,1	3	4	V	
I _{DSS}	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V},$ $T_i = 25 (125) ^{\circ}\text{C}$		50 (300)	250 (1000)	μΑ	
I_{GSS}	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$		10	100	nA	
R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 130 \text{ A}$		7	8,5	mΩ	
g _{fs}	V _{DS} = 25 V, I _D = 130 A	60	75		S	
C _{CHC}	V _{GS} = 0, V _{DS} = 25 V, f = 1 MHz			160	pF	
C _{iss}			10	13	nF	
C _{oss}			5	7,5	nF	
C _{rss}			1,8	2,7	nF	
L _{DS}				20	nΗ	
t _{d(on)}	V _{DD} = 50 V, I _D = 130 A,		60		ns	
t _r	$V_{GS} = 10 \text{ V}, R_{G} = 3.3 \Omega$		220		ns	
$t_{d(off)}$			270		ns	
t _f			200		ns	
Inverse diode						
V_{SD}	$I_F = 400 \text{ A}; V_{GS} = 0 \text{ V}$		1,25	1,6	V	
t _{rr}	T _j = 25 (150) °C		400		ns	
Q_{rr}	$T_{j}^{\prime} = 25 ^{\circ}\text{C}$		3,5		μC	
I _{rr}	T _j = 150 °C				Α	
Thermal characteristics						
R _{th(j-c)}	per MOSFET			0,18	K/W	
R _{th(c-s)}	$\rm M_{\rm s}$, surface 10 μm , per module			0,05	K/W	
Mechanical data						
M_s	to heatsink (M6)	4		5	Nm	
M_t	for terminals (M5)	2,5		3,5	Nm	
w				130	g	

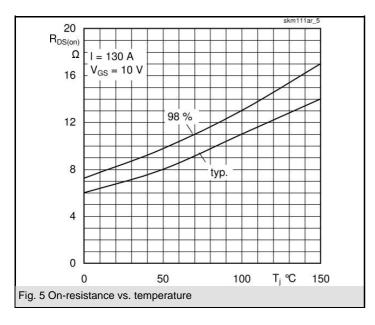


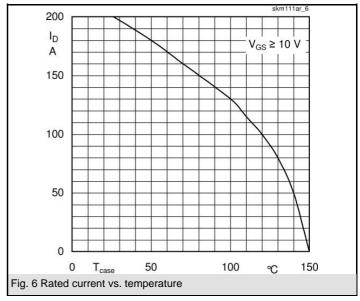


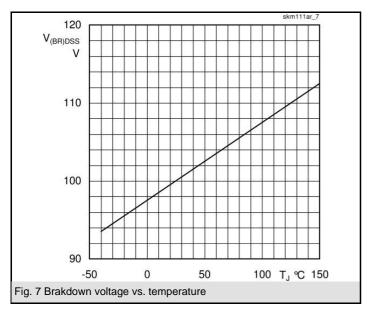


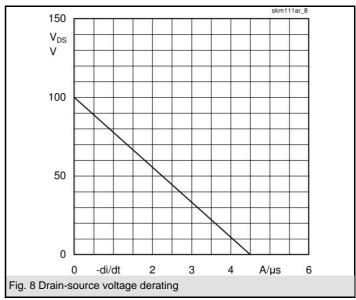


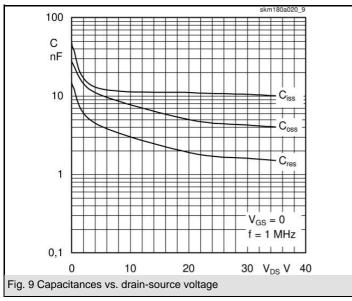


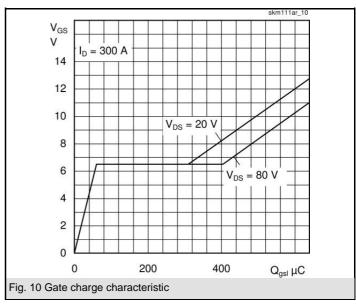


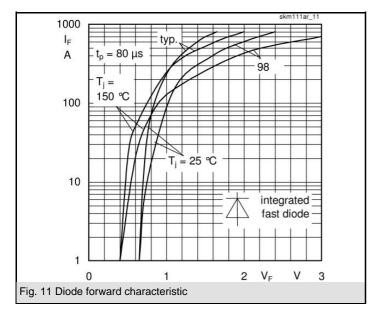


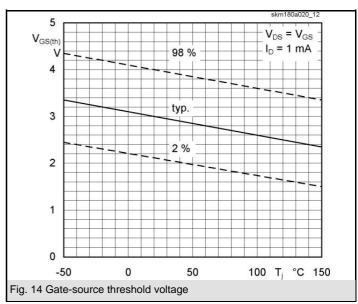


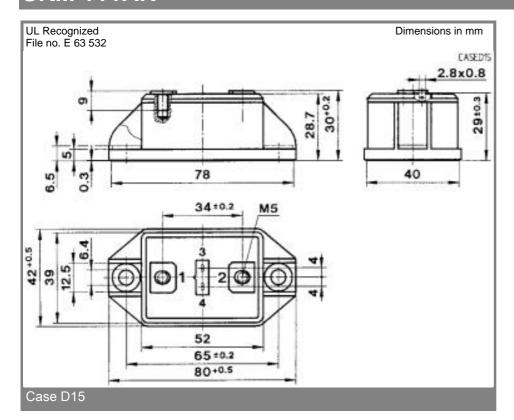


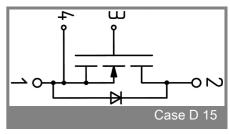












This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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